# 2-Input NAND **Schmitt-Trigger**

The MC74VHC1G132 is a single gate CMOS Schmitt NAND trigger fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The MC74VHC1G132 input structure provides protection when voltages up to 7V are applied, regardless of the supply voltage. This allows the MC74VHC1G132 to be used to interface 5 V circuits to 3 V circuits.

The MC74VHC1G132 can be used to enhance noise immunity or to square up slowly changing waveforms.

- High Speed:  $t_{PD} = 3.6 \text{ ns}$  (Typ) at  $V_{CC} = 5 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu A \text{ (Max)}$  at  $T_A = 25 \text{°C}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 68; Equivalent Gates = 16

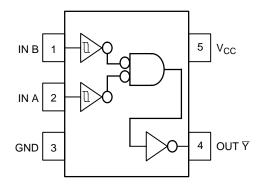


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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#### **MARKING DIAGRAMS**





d = Date Code

TSOP-5/SOT-23/SC-59 **DT SUFFIX CASE 483** 



Pin 1

d = Date Code

	PIN ASSIGNMENT						
1	IN B						
2	IN A						
3	GND						
4	OUT $\overline{Y}$						
5	V <sub>CC</sub>						

#### **FUNCTION TABLE**

Inp	uts	Output
Α	В	Y
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol		Value	Unit	
V <sub>CC</sub>	DC Supply Voltage	-0.5  to  +7.0	V	
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage		$-0.5$ to $V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current		±20	mA
I <sub>OK</sub>	DC Output Diode Current		±20	mA
I <sub>OUT</sub>	DC Output Sink Current		± 12.5	mA
Icc	DC Supply Current per Supply Pin		±25	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Cas	260	°C	
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance	SC70-5/SC-88A (Note 1) TSOP-5	350 230	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°	C SC70-5/SC-88A TSOP-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>LATCH-UP</sub>	Latch-Up Performance	Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage		2.0	5.5	V
V <sub>IN</sub>	DC Input Voltage		0.0	5.5	V
V <sub>OUT</sub>	DC Output Voltage		0.0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range		-55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> = V <sub>CC</sub> =	3.3 V ± 0.3 V 5.0 V ± 0.5 V	0	100 20	ns/V

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

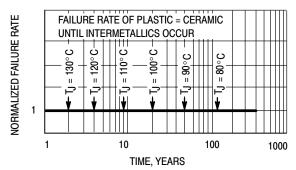


Figure 3. Failure Rate vs. Time Junction Temperature

#### DC ELECTRICAL CHARACTERISTICS

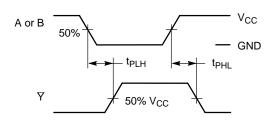
			v <sub>cc</sub>	1	<sub>A</sub> = 25°(	;	T <sub>A</sub> ≤	85°C	-55 ≤ T <sub>A</sub>	≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>T+</sub>	Positive Threshold Voltage		3.0 4.5 5.5	1.50 2.35 2.80	1.88 2.66 3.21	2.25 3.10 3.70	1.50 2.35 2.80	2.25 3.10 3.70	1.50 2.35 2.80	2.25 3.10 3.70	V
V <sub>T-</sub>	Negative Threshold Voltage		3.0 4.5 5.5	0.65 1.10 1.45	1.03 1.62 2.02	1.40 2.10 2.60	0.65 1.10 1.45	1.40 2.10 2.60	0.65 1.10 1.45	1.40 2.10 2.60	V
V <sub>H</sub>	Hysteresis Voltage		3.0 4.5 5.5	0.30 0.40 0.50	0.85 1.05 1.20	1.60 2.00 2.25	0.30 0.40 0.50	1.60 2.00 2.25	0.30 0.40 0.50	1.60 2.00 2.25	V
V <sub>OH</sub>	Minimum High–Level Output Voltage I <sub>OH</sub> = –50µA	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50  \mu\text{A}$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		I <sub>OH</sub> = -4 mA I <sub>OH</sub> = -8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V <sub>OL</sub>	Maximum Low–Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50  \mu\text{A}$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	٧
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	_	_	1.0		20		40	μΑ

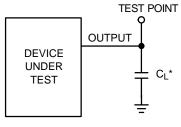
## AC ELECTRICAL CHARACTERISTICS $C_{load} = 50$ pF, Input $t_r/t_f = 3.0$ ns

			T <sub>A</sub> = 25°C		<b>T</b> <sub>A</sub> ≤ 85° <b>C</b>		$-55 \le T_A \le 125$ °C				
Symbol	Parameter	Test Condit	tions	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay,	$V_{CC} = 3.3 \pm 0.3 \text{ V}$	$C_L = 15 pF$ $C_L = 50 pF$		4.6 6.1	11.9 15.4	1.0 1.0	14.0 17.5	1.0 1.0	16.1 19.6	ns
	A or B to $\overline{Y}$	$V_{CC} = 5.0 \pm 0.5 \text{ V}$	$C_L = 15 pF$ $C_L = 50 pF$		3.6 4.3	7.7 9.7	1.0 1.0	9.0 11.0	1.0 1.0	10.3 12.3	
C <sub>IN</sub>	Maximum Input Capacitance				5.5	10		10		10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	11	pF

<sup>6.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.





\*Includes all probe and jig capacitance

Figure 4. Switching Waveforms

Figure 5. Test Circuit

### **DEVICE ORDERING INFORMATION**

	Device Nomenclature							
Device Order Number	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size
MC74VHC1G132DFT1	МС	74	VHC1G	132	DF	T1	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1G132DFT2	МС	74	VHC1G	132	DF	T2	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1G132DTT1	МС	74	VHC1G	132	DT	T1	TSOPS / SOT-23 / SC-59	178 mm (7") 3000 Unit

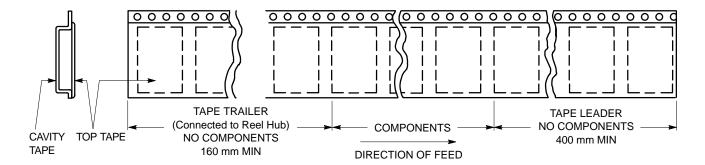


Figure 6. Tape Ends for Finished Goods

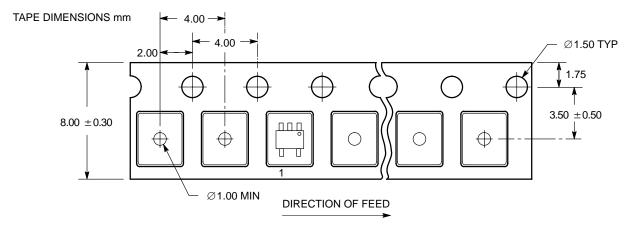


Figure 7. SC-70-5/SC-88A/SOT-353 DFT1 Reel Configuration/Orientation

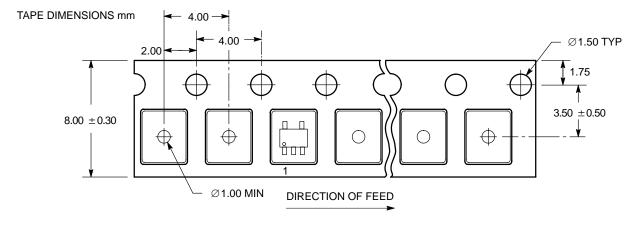


Figure 8. SC-70/SC-88A/SOT-353 DFT2 and SOT23-5/TSOP-5/SC59-5 DTT1 Reel Configuration/Orientation

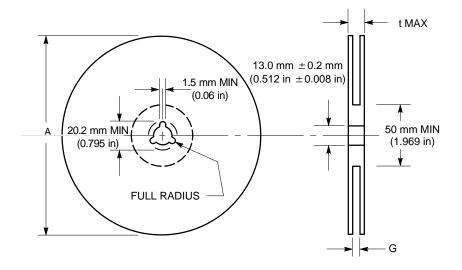


Figure 9. Reel Dimensions

### **REEL DIMENSIONS**

Tape Size	T and R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

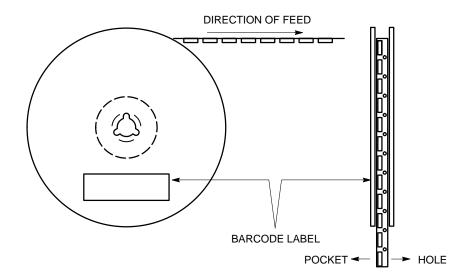
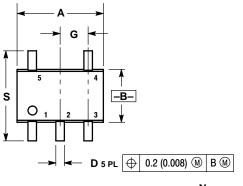


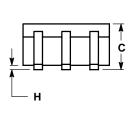
Figure 10. Reel Winding Direction

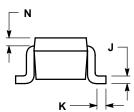
### **PACKAGE DIMENSIONS**

#### SC-88A / SOT-353 / SC-70 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-02 ISSUE F

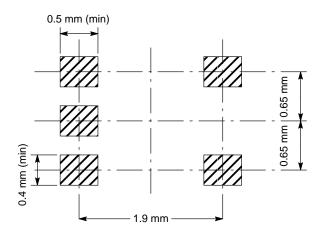






- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

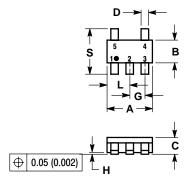
	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
C	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008	REF	0.20 REF		
S	0.079	0.087	2.00	2.20	

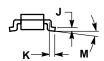


#### PACKAGE DIMENSIONS

#### TSOP-5 / SOT-23 / SC-59 DT SUFFIX

5-LEAD PACKAGE CASE 483-01 ISSUE B

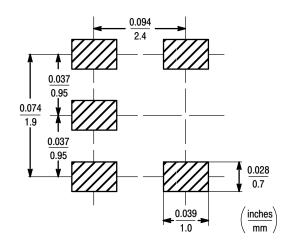




#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.1142	0.1220	
В	1.30	1.70	0.0512	0.0669	
С	0.90	1.10	0.0354	0.0433	
D	0.25	0.50	0.0098	0.0197	
G	0.85	1.05	0.0335	0.0413	
Н	0.013	0.100	0.0005	0.0040	
J	0.10	0.26	0.0040	0.0102	
K	0.20	0.60	0.0079	0.0236	
L	1.25	1.55	0.0493	0.0610	
M	0 °	10°	0°	10°	
S	2.50	3.00	0.0985	0.1181	



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